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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Atty. Dkt. No. 5201-24300
01-120

Inventor(s):

Steve K. Hsiung
Kevan V. Tan

Title: SEMICONDUCTOR DEVICE
PACKAGE SUBSTRATE
PROBE FIXTURE

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**CERTIFICATE OF EXPRESS MAIL
UNDER 37 C.F.R. § 1.10**

"Express Mail" mailing label no. EL893865919US
Date of Deposit: June 19, 2001

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Derrick Brown

UTILITY PATENT APPLICATION TRANSMITTAL

(For new non-provisional applications under 37 CFR § 1.53(b))

Enclosed are the following items:

1. A fee authorization for the amount of \$710.00. The filing fee is calculated below.

Total Claims	20	-20 =	0	x \$18.00 =	\$0.00
Independent Claims	3	-3 =	0	x \$80.00 =	\$0.00
Multiple Dependent Claims				Fee:	
				Basic Fee:	\$710.00
				Total:	\$710.00

2. Request & Certification under 35 U.S.C. 122(b)(2)(B)(i).
3. Patent application which includes: 14 pg. disclosure; 4 pg. claims (1-20); 1 pg. abstract.
4. Informal drawings of Figs. 1-5 on 6 sheets.
5. Newly executed Declaration/Power of Attorney.
6. Newly executed Assignment w/cover sheet.
7. Return receipt postcard.

Respectfully submitted,

Kevin L. Daffer
Reg. No. 34,146
Attorney for Applicants

Conley, Rose & Tayon
P.O. Box 398
Austin, TX 78767-0398
Date: June 19, 2001

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Derrick Brown

FEE AUTHORIZATION

Assistant Commissioner for Patents
Washington, D.C. 20231

The Commissioner is hereby authorized to charge the following fee to LSI Logic Corporation deposit account no. 12-2252/01-120. A duplicate of this page is enclosed.

Item:	Filing fee
Amount:	\$710.00
Atty. Dkt. No.	5201-2430

Atty. Dkt. No. 5201-24300

Respectfully submitted,

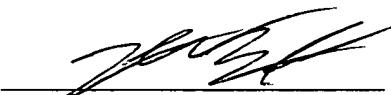
Kevin L. Daffer

Reg. No. 34,146

Attorney for Applicants

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Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

<p style="text-align: center;">CERTIFICATE OF EXPRESS MAIL UNDER 37 C.F.R. §1.10</p> <p>"Express Mail" mailing label number: EL893865919US DATE OF DEPOSIT: June 19, 2001</p> <p>I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. §1.10 on the date indicated above and is addressed to:</p> <p style="text-align: center;">Assistant Commissioner for Patents Box Patent Application Washington, DC 20231</p> <p style="text-align: center;"> Derrick Brown</p>	<p style="text-align: center;">REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%;">Atty Docket Number:</td> <td style="width: 50%;">5201-24300</td> </tr> <tr> <td>First Named Inventor:</td> <td>Steve K. Hsiung et al.</td> </tr> <tr> <td>Title:</td> <td>SEMICONDUCTOR DEVICE PACKAGE SUBSTRATE PROBE FIXTURE</td> </tr> </table>	Atty Docket Number:	5201-24300	First Named Inventor:	Steve K. Hsiung et al.	Title:	SEMICONDUCTOR DEVICE PACKAGE SUBSTRATE PROBE FIXTURE
Atty Docket Number:	5201-24300						
First Named Inventor:	Steve K. Hsiung et al.						
Title:	SEMICONDUCTOR DEVICE PACKAGE SUBSTRATE PROBE FIXTURE						

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

June 19, 2001

Date


Kevin L. Daffer, Reg. No. 34,146

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.